

Title (en)  
STRIP COATING METHOD

Title (de)  
VERFAHREN ZUR BANDBESCHICHTUNG

Title (fr)  
PROCEDE D'APPLICATION DE REVETEMENT SUR UNE BANDE

Publication  
**EP 1794339 B1 20110706 (DE)**

Application  
**EP 05781753 A 20050824**

Priority

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- DE 102004041111 A 20040824
- DE 102004045035 A 20040915
- DE 102004060425 A 20041214

Abstract (en)  
[origin: WO2006021437A1] The invention relates to a strip coating method according to which the strip is guided through two opposite coils of a strip guiding device upstream or downstream of a coating device. Said strip guiding device comprises a position sensor for determining the position of the strip between the coils, current suppliers for the coils and a layer thickness sensor for determining the layer thickness of the coating applied to the strip. The inventive method comprises the following steps: determining a desired layer thickness profile, determining an actual layer thickness profile using the layer thickness sensor, determining a layer thickness control variable by comparing the actual layer thickness profile with the desired layer thickness profile, determining a desired position value for the strip position between the opposite coils using a higher order layer thickness controller whose input signal is the layer thickness control variable, determining an actual position value of the strip between the opposite coils using the position sensor, determining a position control difference by comparing the actual position value with the desired position value, impinging at least one of the coils with current, the current being adjusted in accordance with the output signal of a position controller whose input signal is the position control variable.

IPC 8 full level  
**C23C 2/20** (2006.01)

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**C23C 2/0035** (2022.08 - EP US); **C23C 2/14** (2013.01 - EP US); **C23C 2/20** (2013.01 - EP); **C23C 2/51** (2022.08 - EP US); **C23C 2/52** (2022.08 - EP US); **C23C 2/5245** (2022.08 - EP US); **B65H 2557/2644** (2013.01 - EP)

Cited by  
US10036338B2; US10124750B2; US10309287B2; US10235479B2; US9650934B2; DE102016222230A1; WO2018036908A1; US10503128B2; US10272779B2; US11180024B2; US10415492B2; US11506138B2; DE102016222224A1; WO2017144194A1; US10982307B2; US11057213B2; US9677493B2; US10309281B2; US10423131B2; US11144017B2; US11687047B2; US10621291B2; US11156180B2; US11619189B2; US11687688B2

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